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(12) **United States Design Patent**  
**Sasaki et al.**

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(54) **ATTRACTING PLATE OF AN  
ELECTROSTATIC CHUCK FOR  
SEMICONDUCTOR MANUFACTURING**

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Tokyo (JP)

(\*\*) Term: **14 Years**

(21) Appl. No.: **29/276,663**

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(30) **Foreign Application Priority Data**

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(51) **LOC (9) Cl.** ..... **13-03**

(52) **U.S. Cl.** ..... **D13/182**

(58) **Field of Classification Search** ..... D13/182;  
156/345.53; 279/128; 361/234  
See application file for complete search history.

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Maier & Neustadt, P.C.

(57) **CLAIM**

The ornamental design for an attracting plate of an electrostatic chuck for semiconductor manufacturing, as shown and described.

**DESCRIPTION**

FIG. 1 is a front elevational view of an attracting plate of an electrostatic chuck for semiconductor manufacturing, showing our new design;

FIG. 2 is a rear elevational view thereof;

FIG. 3 is a top plan view thereof;

FIG. 4 is an enlarged view thereof taken along sections A—A and B—B in FIG. 1;

FIG. 5 is a right side elevational view thereof;

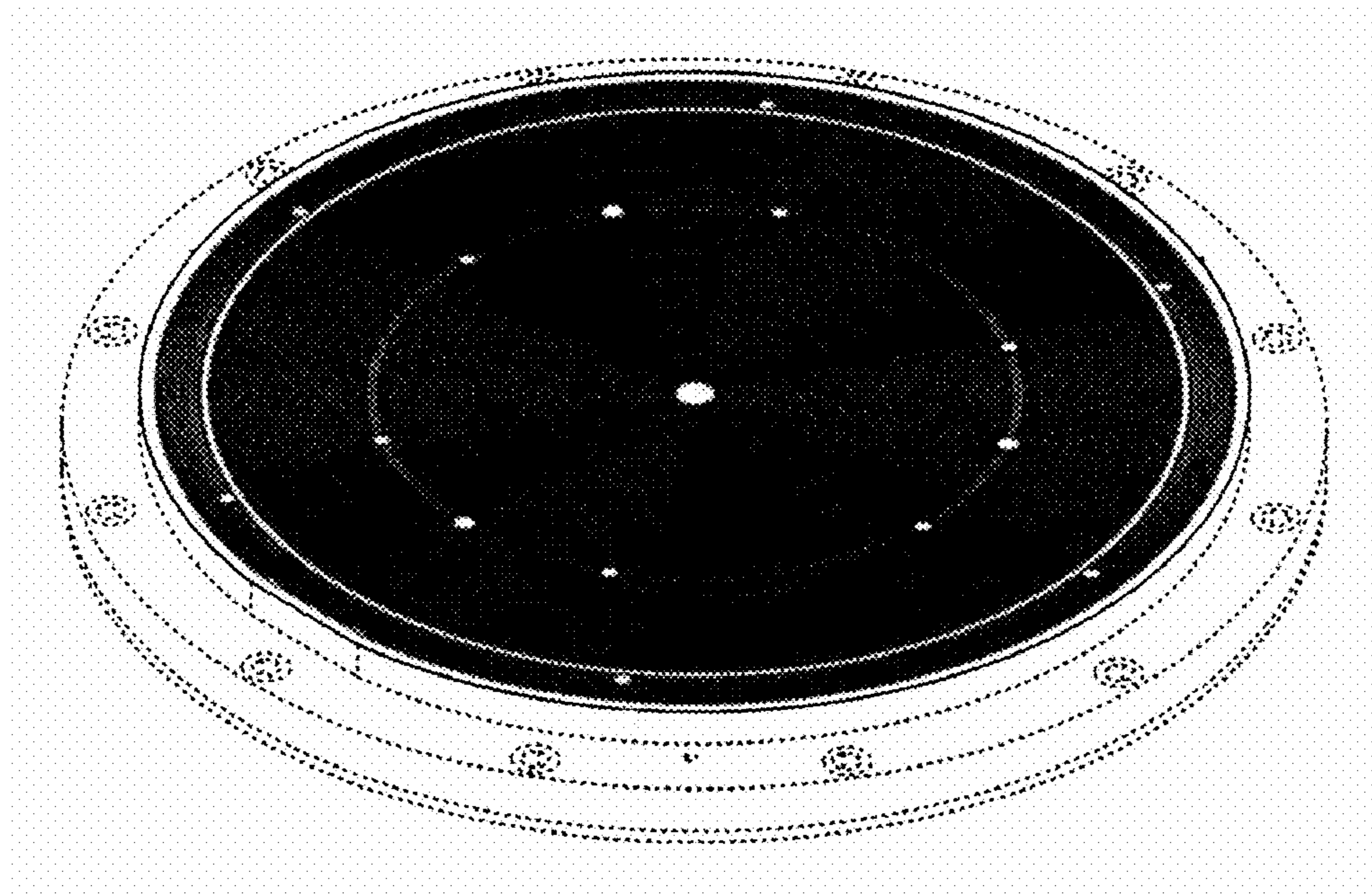
FIG. 6 is a left side elevational view thereof;

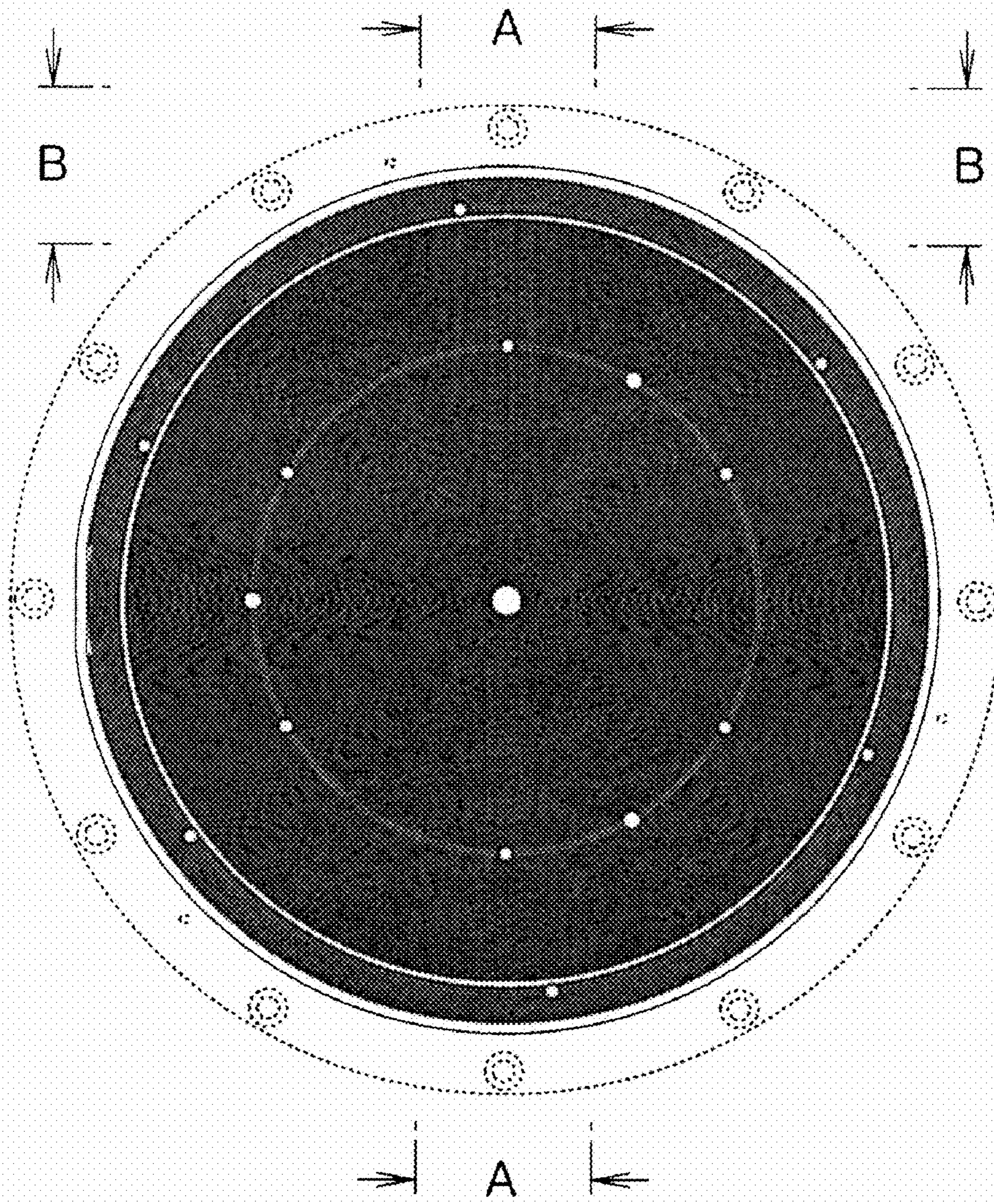
FIG. 7 is a cross-sectional view taken along line 7—7 in FIG. 4 with portions of the internal mechanism omitted; and,

FIG. 8 is a front perspective view thereof.

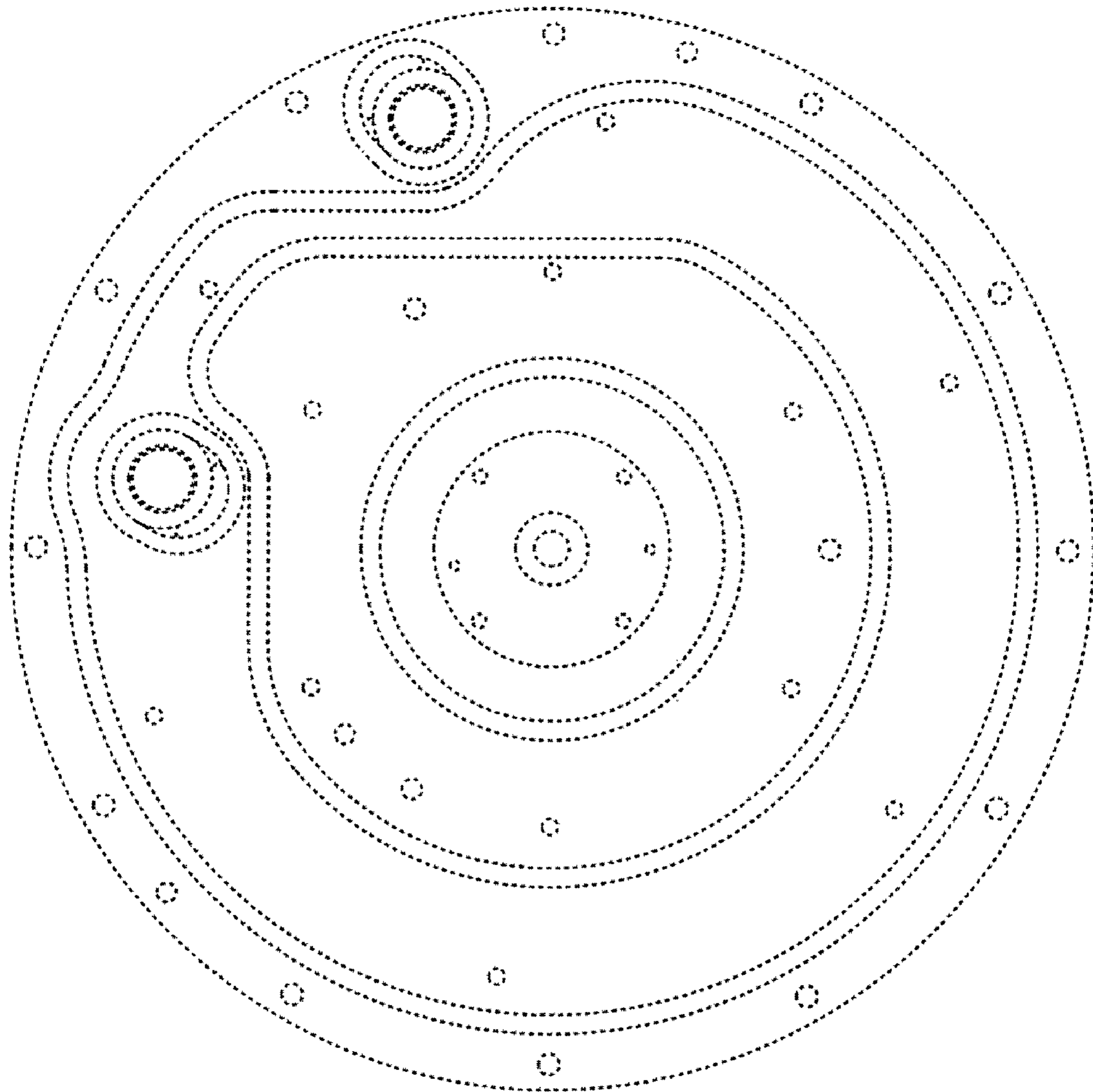
The broken line showing in the figures is for illustrative purposes only and forms no part of the claimed design.

**1 Claim, 8 Drawing Sheets**

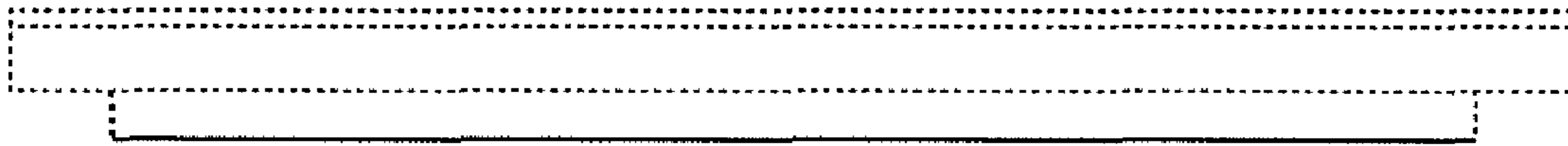




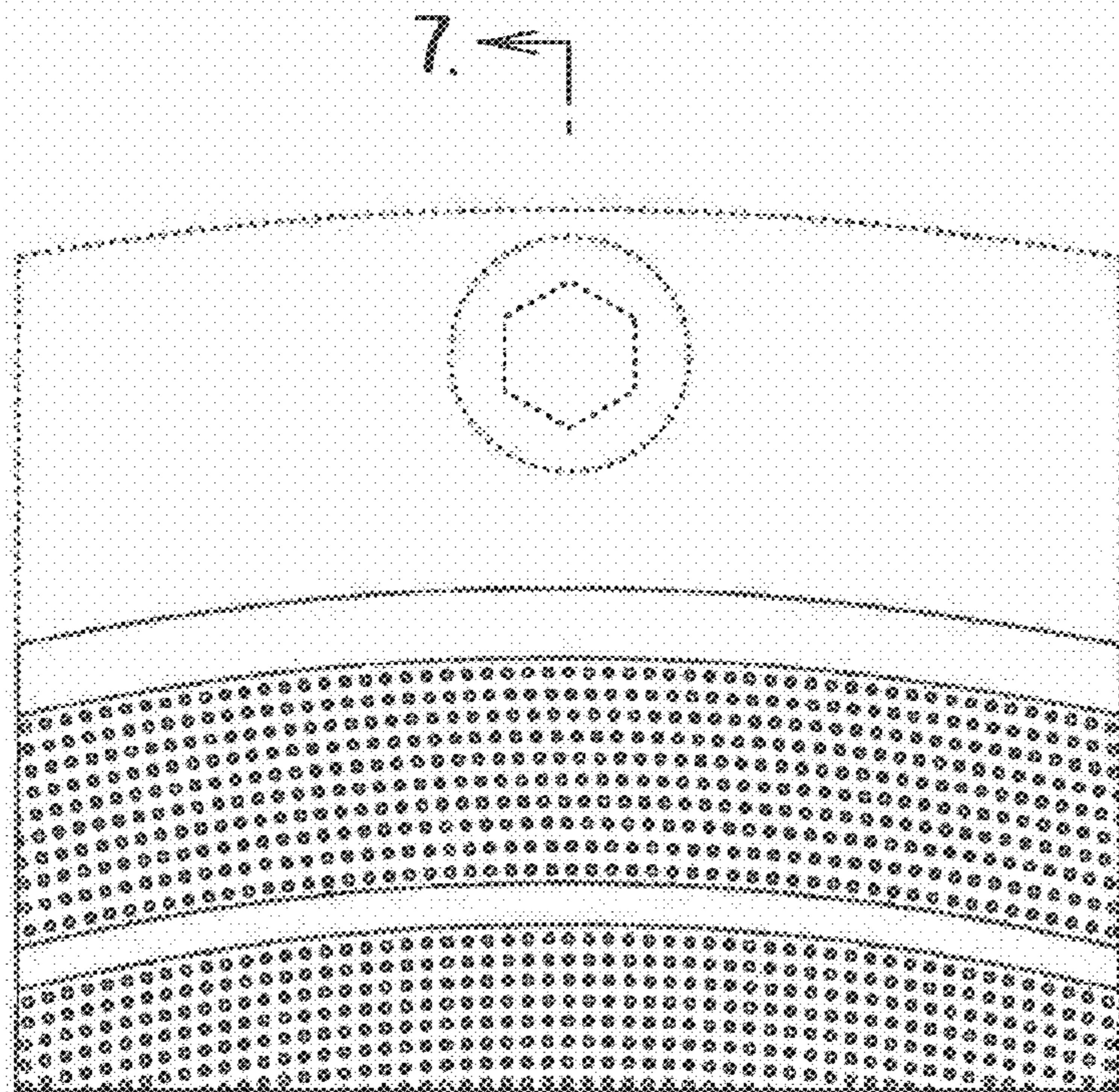
**FIG. 1**



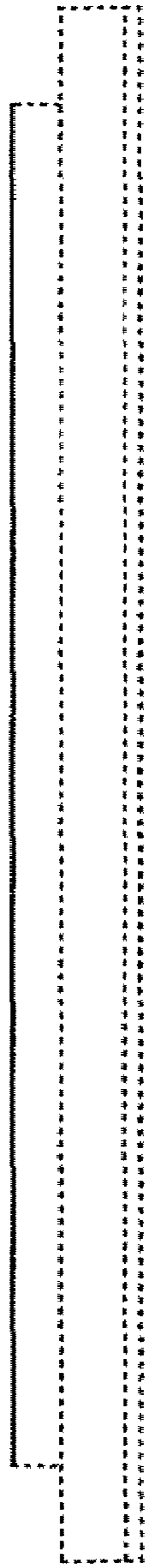
**FIG. 2**



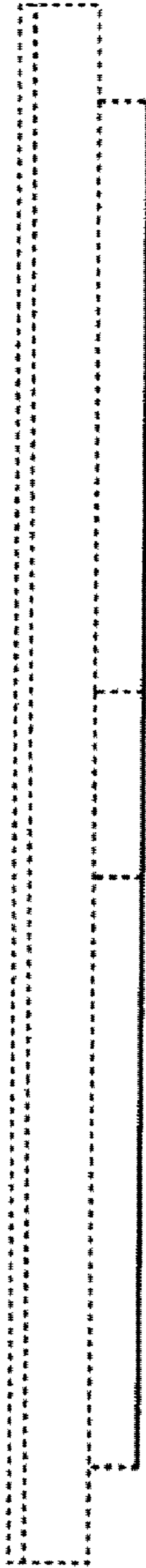
***FIG. 3***



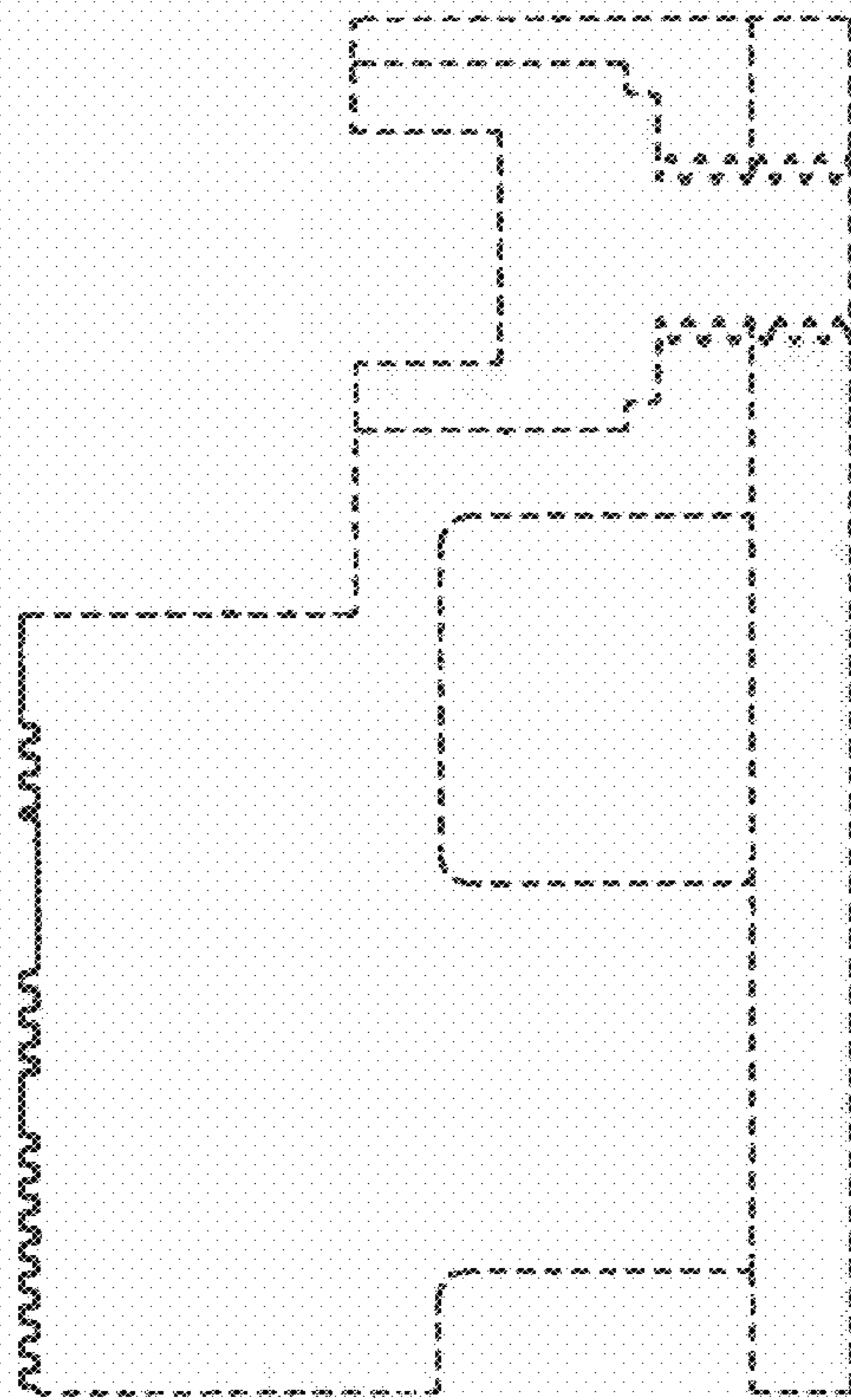
*FIG. 4*



***FIG. 5***

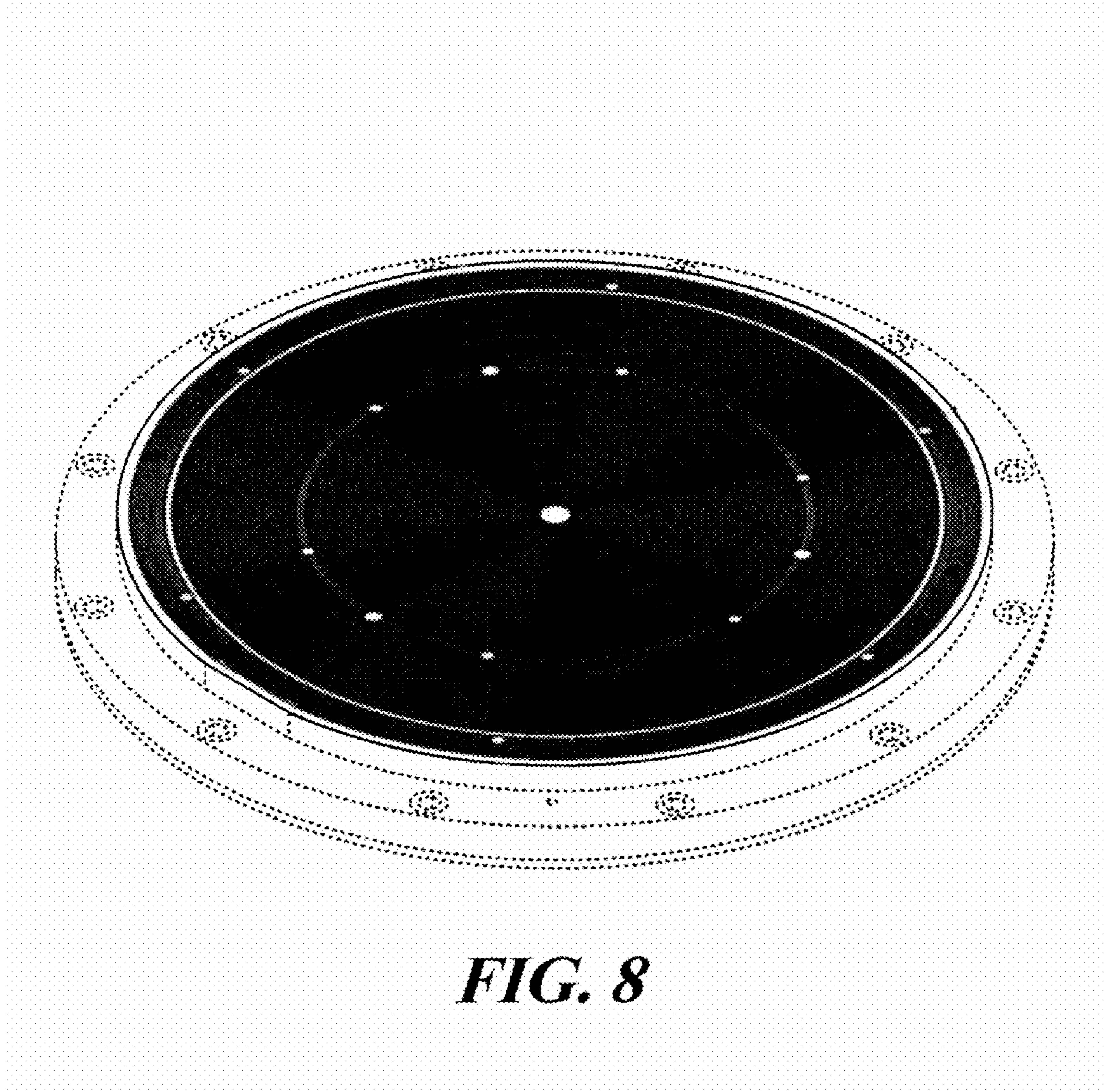


***FIG. 6***



***FIG. 7***





**FIG. 8**